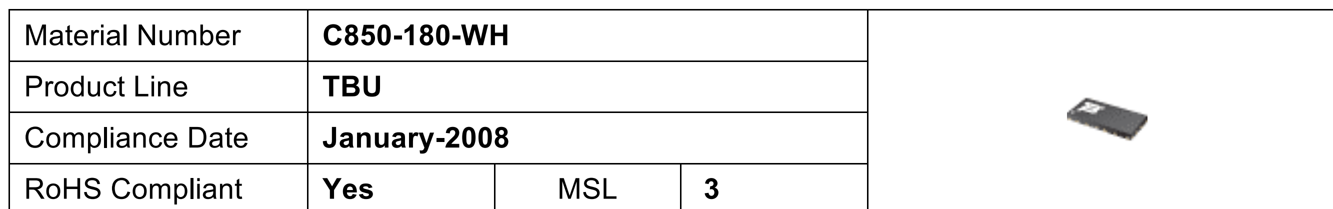
MATERIAL DECLARATION SHEET



Material Number	C850-180-WH		
Product Line	**TBU**		
Compliance Date	**January-2008**		
RoHS Compliant	**Yes**	MSL	**3**

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Semiconductor Device	Silicon Chip	6.68	Doped silicon	7440-21-3	100	6.96	6.96
2	Lead Frame	Copper alloy with silver plating	47.28	Copper	7440-50-8	97.29	47.97	49.31
				Chromium III	7440-47-3	0.25	0.12	
				Tin	7440-31-5	0.25	0.12	
				Zinc	7440-66-6	0.22	0.11	
				Silver (plating)	7440-22-4	2.0	0.99	
3	Bond wire	Gold wire	0.23	Gold	7440-57-5	100	0.24	0.24
4	Die Attach	Adhesive	1.74	Di-ester resin	proprietary	3	0.05	1.81
				Functionalized ester	proprietary	7	0.13	
				Polymeric compound	proprietary	3	0.05	
				Silver	7440-22-4	87	1.58	
5	Mold compound (halogen-free)	Epoxy resin	37.02	Silica fused	60676-86-0	90.5	34.94	38.6
				Epoxy resin	proprietary	4.7	1.81	
				Phenolic resin	proprietary	4.7	1.81	
				Carbon black	1333-86-4	0.1	0.04	
6	Matte tin plating	matte tin	2.94	Tin	7440-31-5	100	3.07	3.07
		Total weight	**95.89**					

This Document was updated on: January 12, 2010

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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